Low-pressure plasma system V55-G
Standard system for cleaning, activation, etching or coating

The unit is integrated in a 19” rack, which is equipped with rollers and height-adjustable feet.

The system can be used for the surface treatment methods cleaning, activation, etching and coating.

### Options
- Vacuum pump
- Ozone trap
- Up to two additional gas inlets
- Additional excitation frequencies (40 kHz, 13.56 MHz)
- Rotary drum for the treatment of bulk material
- Rotary table
- Pullout door
- Automatic door opening
- Soft start and slow vent

### System features
- USB port
- Ethernet interface
- Remote maintenance (VPN)
- Microwave coupling from the top
- Swing door

### Technical data
- Dimensions of the system (W x D x H): 670 x 900 x 1,850 mm
- Dimensions of the chamber (W x D x H): 400 x 460 x 340 mm
- Plasma excitation frequency: Microwave (2.45 GHz)
- Microwave power: 100-1,200 W
- Gas inlets with mass-flow-control: 2 channels
- Power supply: 230/400 V, 50/60 Hz
- Power input: 2,2 kVA
- Vacuum gauge: Baratron

The variable standard system V55-G has a high process operating flexibility because of its two gas channels and three optional plasma generating frequencies.